

Amendments to the Claims:

Please amend the claims as follows:

1. (Currently amended) ~~In a fill composition for coating contact or via holes formed in a base material to protect the base material during etching processes; The combination of:~~
a microelectronic substrate having a surface; and
a fill composition adjacent said microelectronic substrate surface, wherein said composition
comprises: the composition including
a quantity of solid components including a polymer binder[[,]];
and a solvent system for said solid components, ~~the improvement which~~
comprises:
said composition;
being at least about 70% removed from the base material when
subjected to a pre-bake thermal stability test; and
~~said composition~~ having less than about 15% shrinkage when
subjected to a film shrinkage test.
2. (Currently amended) The ~~composition~~combination of claim 1, said solvent system boiling point being less than about 160°C.

3. (Currently amended) The ~~composition~~combination of claim 1, said solvent system having a flash point of greater than about 85°C.

4. (Currently amended) The ~~composition~~combination of claim 1, wherein said polymer binder has a molecular weight of less than about 80,000.

5. (Currently amended) The ~~composition~~combination of claim 1, wherein said polymer binder comprises polyacrylate.

6. (Currently amended) The ~~composition~~combination of claim 1, wherein said solvent system includes a solvent selected from the group consisting of alcohols, ethers, glycol ethers, amides, esters, ketones, and mixtures thereof.

7. (Currently amended) The ~~composition~~combination of claim 6, wherein said solvent is PGME.

8. (Currently amended) The ~~composition~~combination of claim 1, wherein said composition includes a cross-linking agent.

9. (Currently amended) The ~~composition~~combination of claim 8, wherein said cross-linking agent is selected from the group consisting of aminoplasts, epoxides, isocyanates, acrylics, and mixtures thereof.

10. (Currently amended) The ~~composition~~combination of claim 1, wherein said polymer binder includes a cross-linking moiety.

11. (Currently amended) The ~~composition~~combination of claim 8, wherein the cross-linking temperature of said composition is from about 150-220°C.

12. (Currently amended) The ~~composition~~combination of claim 1, wherein said solid components, when mixed together, have a melting point of less than about 200°C.

13. (Currently amended) The ~~composition~~combination of claim 1, said composition and said base material each having respective etch rates, said composition etch rate being approximately equal to said base material etch rate.

14. (Currently amended) The ~~composition~~combination of claim 1, said composition further including a light-absorbing dye.

15. (Currently amended) The ~~composition~~combination of claim 14, wherein said dye is bonded to said polymer binder.

16. (Currently amended) The ~~composition~~combination of claim 1, said composition further including a wetting agent.

17. (Currently amended) The ~~composition~~combination of claim 16, wherein said wetting agent is a fluorinated surfactant.

18. (New) The combination of claim 1, wherein said microelectronic substrate is selected from the group consisting of silicon and GaAs.

19. (New) The combination of claim 1, wherein said microelectronic substrate has a contact or via hole having a bottom wall and side walls, said fill composition being on at least a portion of said bottom wall and said side walls.